



**Journal of
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Guest Editorial

Special Issue on InterPACK2023

The International Technical Conference on Packaging and Integration of Electronic and Photonic Microsystems (InterPACK) is the leading international conference for the dissemination of basic and applied research in the broad field of electronics and photonics packaging. Since its inception in 1992, the InterPACK conference has served as the primary forum for members of the American Society of Mechanical Engineers Electronic and Photonic Packaging Division (ASME EPPD) to exchange knowledge and ideas, guiding collaborative efforts between academia, national labs, and industry.

The 2023 ASME InterPACK Conference was held in San Diego from October 23rd through October 26th. The program contained more than 210 technical presentations, 90 original technical papers, tutorials, panel discussions, workshops, and plenary talks aligned with the following areas: (1) heterogeneous integration, (2) data centers and modular edge systems, (3) electronics packaging, (4) power/RF electronics and photonics, (5) multiscale thermal transport and energy storage, (6) flexible, wearable, and printed electronics, and (7) transportation systems, AI, and machine learning.

This Special Issue of the ASME Journal of Electronic Packaging includes selected papers from the conference that represent cutting-edge research being conducted in these focus areas. All submitted manuscripts went through an independent peer review process in accordance with the editorial standards of the ASME. We expect

that this series of papers will help to educate the wider EPPD and scientific communities on the exciting topics covered in the conference. We would also like to thank the authors who chose to publish their work in this Special Issue, as well as the reviewers. We would also like to thank Professor Ricky Lee and Andrew Clarke from the ASME Editorial team for their assistance with the organization of this collection of manuscripts.

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